

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3537871

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Ching-Wen Hung</td><td>09/16/2015</td></tr><tr><td>Chih-Sen Huang</td><td>09/16/2015</td></tr><tr><td>Yi-Wei Chen</td><td>09/16/2015</td></tr><tr><td>Shih-Fang Tzou</td><td>09/16/2015</td></tr></tbody></table>	Name	Execution Date	Ching-Wen Hung	09/16/2015	Chih-Sen Huang	09/16/2015	Yi-Wei Chen	09/16/2015	Shih-Fang Tzou	09/16/2015	
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Chih-Sen Huang	09/16/2015										
Yi-Wei Chen	09/16/2015										
Shih-Fang Tzou	09/16/2015										
RECEIVING PARTY DATA											
Name:	UNITED MICROELECTRONICS CORP.										
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park										
City:	Hsin-Chu City										
State/Country:	TAIWAN										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>14862165</td></tr></tbody></table>	Property Type	Number	Application Number:	14862165							
Property Type	Number										
Application Number:	14862165										
CORRESPONDENCE DATA											
Fax Number:	(703)997-4517										
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>											
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Email:	Patent.admin.uspto.cr@naipo.com										
Correspondent Name:	WINSTON HSU										
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Address Line 4:	MERRIFIELD, VIRGINIA 22116										
ATTORNEY DOCKET NUMBER:	NAUP2588USA										
NAME OF SUBMITTER:	KATE YEH										
SIGNATURE:	/KATE YEH/										
DATE SIGNED:	09/23/2015										
Total Attachments: 8 source=2363177#page1.tif source=2363177#page2.tif source=2363177#page3.tif source=2363177#page4.tif											

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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:
METHOD FOR FORMING SEMICONDUCTOR DEVICE

As the below named inventor, I hereby declare that:
This declaration is directed to:

- ☒ The attached application, or
- ☐ United States application number _____ filed on _____, or
- ☐ PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this SEP 16 2015 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Ching-Wen Hung**

Date: **SEP 16 2015**

Signature: Ching-Wen Hung

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chih-Sen Huang**

Date: **SEP 16 2015**

Signature: Chih-Sen Huang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yi-Wei Chen**

Date:

SEP 16 2015

Signature:

Yi-Wei Chen

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Shih-Fang Tzou**

Date: **SEP 16 2015**

Signature: Shih-Fang Tzou